Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

2

Listing of Claims:

- 1. (Currently amended) A vertical-cavity device comprising:
 - (a) a chip comprising an active semiconductor layer for providing configured to provide optical gain;
 - (b) a first mirror arranged on a first side of the active layer;
 - (c) a second mirror arranged on a second side of the active layer, opposite to the first mirror, and forming with at least the first mirror an optically resonant cavity that passes through the active layer in a direction out of the plane of the active layer; and
 - (d) a heatspreader for removing heat from the active layer, the heatspreader being arranged inside the cavity and having a first surface adjacent to the chip and a second surface opposite to the first surface, the heatspreader being transparent to light of wavelengths in an operating bandwidth of the device[[;]] and having at least one characterised in that, in addition to removing heat from the active layer, the heatspreader also has one or more further selected property that has a further selected effect on light output from the device.
- 2. (Original) A device as claimed in claim 1, in which the heatspreader is birefringent and the further selected effect is on the polarisation of the output light.
- 3. (Original) A device as claimed in claim 2, in which the difference in between the refractive indices of the

heatspreader's slow and fast polarisation axes is greater than 0.01.

- 4. (Currently amended) A device as claimed in claim 2 $\frac{1}{2}$ elaim 3, comprising a further element that limits the output light to a linear polarisation.
- 5. (Currently amended) A device as claimed in any of claims 1 to 4 claim 1, in which the heatspreader has a nonlinear optical response.
- 6. (Currently amended) A device as claimed in any preceding claim 1, in which the shape of the heatspreader provides the further selected effect.
- 7. (Original) A device as claimed in claim 6, in which the second surface of the heatspreader is curved or includes a curved structure.
 - 8. (Currently amended) A device as claimed in $\frac{1}{2}$ and $\frac{1}{2}$, in which the heatspreader focuses or defocuses the output light.
 - 9. (Currently amended) A device as claimed in $\frac{1}{2}$ and $\frac{1}{2}$, in which the heatspreader focuses pump light into the active layer.
 - . 10. (Currently amended) A device as claimed in any preceding claim $\underline{1}$, in which the further selected effect is on light generated in the active semiconductor layer at a fundamental frequency of the device.
 - 11. (Currently amended) A device as claimed in $\frac{1}{2}$ preceding claim $\frac{1}{2}$, in which the selected property of the

heatspreader has been selected to affect the spectrum of the output light.

- 12. (Original) A device as claimed in claim 11, in which the heatspreader has a refractive index that has been selected to provide substantially no refractive index step at the first surface.
- 13. (Original) A device as claimed in claim 12, in which reflectance at the first surface of the heatspreader is less than 5%.
- 14. (Original) A device as claimed in claim 10, in which the heatspreader has a refractive index that has been selected to provide a refractive index step at the first surface.
- 15. (Currently amended) Α device claimed as in any · preceding claim 1, in which the second surface of the heatspreader is at an angle to the layers of the chip.
 - 16. (Currently amended) A device as claimed in any preceding claim 1, in which the heatspreader has a shape selected to provide control of a spatial mode of the output light.
 - 17. (Original) A device as claimed in claim 16, in which the heatspreader focuses or defocuses intracavity light.
 - 18. (Original) A device as claimed in claim 17, in which the second mirror is flat.
 - 19. (Original) A device as claimed in claim 18 in which the second mirror is a MEMS mirror.

- 20. (Currently amended) A device as claimed in $\frac{1}{2}$ preceding claim $\frac{1}{2}$, in which the second surface of the heatspreader has a dielectric coating.
- 21. (Original) A device as claimed in claim 20, in which the dielectric coating is an anti-reflection coating.
- 22. (Currently amended) A device as claimed in claim 20, in which the dielectric coating is a mirror coating and [[it]] forms the second mirror.
- 23. (Currently amended) A device as claimed in $\frac{1}{2}$ and $\frac{1}{2}$, in which the heatspreader has a thickness of less than 1.5 mm.
- 24. (Currently amended) A device as claimed in any preceding claim 1, in which the heatspreader is [[also]] a loss modulator.
 - 25. (Currently amended) A method of manufacturing a vertical-cavity device, comprising:
 - (a) fabricating a chip comprising an active semiconductor layer for providing optical gain;
 - (b) providing a first mirror on a first side of the active layer;
 - (c) providing a second mirror on a second side of the active layer, opposite to the first mirror, which forms with at least the first mirror an optically resonant cavity that passes through the active layer in a direction out of the plane of the active layer;
 - (d) providing in the cavity a heatspreader for removing heat from the active layer, the heatspreader having a first surface adjacent to the chip and a second surface opposite to the first surface, the heatspreader being transparent to

light of wavelengths in the operating bandwidth of the device; and

characterised in that the method also includes the step of

- <u>(e)</u> selecting <u>at least</u> one or more property of the heatspreader to have a selected effect on the output light, in addition to the <u>effects</u> <u>effect</u> of removing heat from the active layer.
- 26. (Original) A method as claimed in claim 25, including the step of forming the second surface of the heatspreader to be curved or to include a curved structure.
- 27. (Original) A method as claimed in claim 26, in which the curved surface is formed by polishing.
- 28. (Original) A method as claimed in claim 26, in which the curved surface or the curved structure is formed by etching.
- 29. (Currently amended) A device manufactured by a method according to any of claims 25 to 28 claim 25.
- 30. (Currently amended) An amplifier or laser including a source of pump light comprising a device according to any of claims 1 to 24 claim 1.
- 31. (Original) An amplifier or laser as claimed in claim 30 that is a Raman amplifier.
- 32. (Currently amended) A vertical cavity device comprising:
 - (a) a chip comprising an active semiconductor layer for providing optical gain;
 - (b) a first mirror arranged on a first side of the active layer suitable for forming with at least a second mirror arranged on a second side of the active layer,

D-3213

opposite to the first mirror, an optically resonant cavity that passes through the active layer in a direction out of the plane of the active layer; and

(c) a heatspreader for removing heat from the active layer, having a first surface adjacent to the active layer and a second surface opposite to the first surface, the heatspreader being transparent to light of wavelengths in an operating bandwidth of the device[[;]] and,

7

characterised in that, in addition to removing heat from the active layer, the heatspreader also has one or more at least one further selected property that has a further selected effect on light output from the device.